

Global Semiconductor Bonding Market Size study & Forecast, by Type (Die Bonder, Wafer Bonder, Flip Chip Bonder) by Process Type (Die-To-Die Bonding, Die-To Wafer Bonding, Wafer-To-Wafer Bonding), by Bonding Technology (Die Bonding Technology, Wafer Bonding Technology), by Application (RF Devices, Mems and Sensors, CMOS Image Sensors, LED, 3D NAND) and Regional Analysis, 2023-2030

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### **Abstracts**

Global Semiconductor Bonding Market is valued approximately at USD 0.91 billion in 2022 and is anticipated to grow with a healthy growth rate of more than 3.60% over the forecast period 2023-2030. Semiconductor bonding is the process of joining two semiconductor materials to create a functional device or structure. This bonding can be achieved through various techniques, and the choice of method depends on the specific application and the properties of the materials involved. Moreover, the rising demand for miniature electronic components, rising adoption of MEMS and sSensors, growing demand for electric and hybrid vehicles that are anticipated to create the lucrative demand for the market during forecast period 2023-2030.

Additionally, the growing demand for electric and hybrid vehicles is a significant factor contributing to the growth of the Semiconductor Bonding Market. The Electric vehicles (EVs) and hybrid electric vehicles (HEVs) rely heavily on power electronics for functions such as motor control, battery management, and power conversion. Semiconductor devices like such as insulated gate bipolar transistors (IGBTs) and power modules play a crucial role in these applications. According to The International Energy Agency, in 2019, the number of Battery Electric Vehicles (BEV) and Plug-in Hybrid Vehicles



(PHEV) sold was 580,000 and 1,500,000, respectively. In 2022, the numbers reached 2,900,000 and 7,300,000, respectively. As a result, the growing demand for EVs is anticipated to propel lucrative demand for the market. Moreover, the growing adoption of IoT and AI in automotive sector, and increased connectivity and 5G adoption is anticipated to create the lucrative opportunity for the market growth. However, the high cost associated with semiconductor bonding solution stifles market growth throughout the forecast period of 2023-2030.

The key regions considered for the Global Semiconductor Bonding Market study includes Asia Pacific, North America, Europe, Latin America, and Middle East & Africa. North America dominated the market in 2022 with largest market share owing to the increasing demand for electronic devices, growing technological advancements and innovations in semiconductor manufacturing, and rise in artificial intelligence (AI) and data centers. Whereas, the Asia Pacific region is expected to grow with the fastest growth rate during the forecast period, owing to factors such as the rising demand for electronic devices, growing expansion of semiconductor industry, increased investments in research and development, and growing adoption of internet of things (IoT).

Major market player included in this report are:

Besemiconductor

SUSS MicroTec SE

Kulicke and Soffa Industries

Shibuara Mechatronics Corporation

**TDK Corporation** 

Palomar Technologies

EV Group (EVG)

SHINKAWA Electric Co., Ltd

Tokyo Electron Limited



Intel Corporation

Recent Developments in the Market:

In April 2021, ASM Pacific Technology has introduced three cutting-edge manufacturing systems that incorporate X-Celeprint's Micro Transfer Printing and ASM AMICRA's high-precision die bonding technology. These systems are designed to facilitate large-scale heterogeneous integration of ultra-thin dies, supporting wafer sizes of up to 300 mm.

Global Semiconductor Bonding Market Report Scope:

Historical Data – 2020 - 2021

Base Year for Estimation – 2022

Forecast period - 2023-2030

Report Coverage - Revenue forecast, Company Ranking, Competitive Landscape, Growth factors, and Trends

Segments Covered – Type, Process Type, Bonding Technology, Application, Region

Regional Scope - North America; Europe; Asia Pacific; Latin America; Middle East & Africa

Customization Scope - Free report customization (equivalent up to 8 analyst's working hours) with purchase. Addition or alteration to country, regional & segment scope\*

The objective of the study is to define market sizes of different segments & countries in recent years and to forecast the values to the coming years. The report is designed to incorporate both qualitative and quantitative aspects of the industry within countries involved in the study.

The report also caters detailed information about the crucial aspects such as driving



factors & challenges which will define the future growth of the market. Additionally, it also incorporates potential opportunities in micro markets for stakeholders to invest along with the detailed analysis of competitive landscape and product offerings of key players. The detailed segments and sub-segment of the market are explained below:

By Type:

Die Bonder

Wafer Bonder

Flip Chip Bonder

By Process Type:

Die-To-Die Bonding

**Die-To Wafer Bonding** 

Wafer-To-Wafer Bonding

By Bonding Technology:

Die Bonding Technology

Wafer Bonding Technology

By Application:

**RF** Devices

Mems and Sensors

**CMOS Image Sensors** 

LED

**3D NAND** 



By Region:	
North America	
U.S.	
Canada	
Europe	
UK	
Germany	
France	
Spain	
Italy	
ROE	
Asia Pacific	
China	
India	
Japan	
Australia	
South Korea	
RoAPAC	
Latin America	
Brazil	

Global Semiconductor Bonding Market Size study & Forecast, by Type (Die Bonder, Wafer Bonder, Flip Chip Bonder....



Mexico

Middle East & Africa

Saudi Arabia

South Africa

Rest of Middle East & Africa



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